

AMENDMENTS TO THE CLAIMS

1. **(Original)** A method of forming an electronic packaging module, comprising:
 - securing a first plurality of integrated circuit chips in a first chip stack, wherein the first chip stack comprises a first lateral face wherein the first lateral face comprises a portion of each chip;
 - securing a second plurality of integrated circuit chips in a second chip stack, wherein the second chip stack comprises a first lateral face wherein the first lateral face comprises a portion of each chip;
 - bonding the first lateral face of the first chip stack to the first lateral face of the second chip stack so as to form a single module;
 - electrically interconnecting the module to a bonding substrate, wherein the bonding substrate comprises external circuitry.
2. **(Original)** The method of Claim 1, further comprising:
 - enclosing said module inside an enclosure;
 - introducing a thermally conductive fluid to said enclosure, said thermally conductive fluid has a thermal conductivity greater than that of air at one atmosphere, wherein said thermally conductive fluid contacts the chip stacks and transfers heat therefrom.
3. **(Original)** The method of Claim 2, wherein introducing said thermally conductive fluid into said enclosure comprises introducing a gas mixture comprising helium and hydrogen.
4. **(Original)** The method of Claim 3, wherein said gas mixture is at a pressure higher than pressure external to the enclosure.
5. **(Original)** The method of Claim 1, wherein securing the first chips in the first chip stack comprises securing one or more chip substrates in a stack in a manner such that a plurality of openings are formed between two adjacent chip substrates in a manner so as to permit a fluid to circulate in a region between the substrates, thereby providing cooling for the chip stack.
6. **(Original)** The method of Claim 1, wherein securing the first chips in the first chip stack comprises securing one or more chip structures having a plurality of air bridge structures formed on a substrate of the chip, wherein said air bridge structures are stabilized and supported by a temporary support material.

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7. **(Original)** The method of Claim 6, further comprising removing the temporary support material stack after electrically connecting the module to the bonding substrate.

8. **(Original)** The method of Claim 6, further comprising removing the temporary support material after bonding the first chip stack to the second chip stack.

Claims 9-13 **(Canceled)**